Quad 2-Input NAND Gate with Schmitt-Trigger Inputs

High-Performance Silicon-Gate CMOS

The MC74HC132A is identical in pinout to the LS132. The device inputs are compatible with standard CMOS outputs; with pull-up resistors, they are compatible with LSTTL outputs.

The HC132A can be used to enhance noise immunity or to square up slowly changing waveforms.

Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements as Defined by JEDEC Standard No. 7A
- Chip Complexity: 72 FETs or 18 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

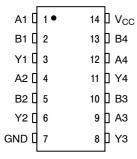


Figure 1. Pin Assignment



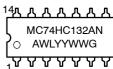
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MARKING DIAGRAMS

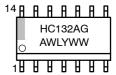


PDIP-14 N SUFFIX CASE 646





SOIC-14 D SUFFIX CASE 751A





1

TSSOP-14 DT SUFFIX CASE 948G



A = Assembly Location

L, WL = Wafer Lot Y, YY = Year

W, WW = Work Week
G or ■ = Pb-Free Package

(Note: Microdot may be in either location)

FUNCTION TABLE

| Inp | Output | |
|-----|--------|---|
| Α | В | Υ |
| L | L | Н |
| L | Н | Н |
| Н | L | Н |
| Н | Н | L |

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

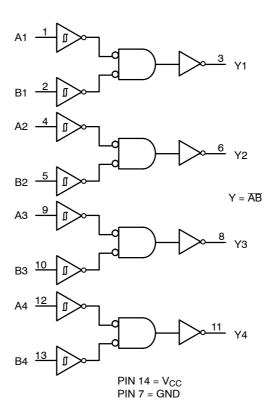


Figure 2. Logic Diagram

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-------------------|-----------------------|-----------------------|
| MC74HC132ANG | PDIP-14 (Pb-Free) | 25 / Tape & Ammo Box |
| MC74HC132ADG | SOIC-14 (Pb-Free) | 55 Units / Rail |
| MC74HC132ADR2G | SOIC-14 (Pb-Free) | 2500 / Tape & Reel |
| MC74HC132ADTG | TSSOP-14 (Pb-Free) | 96 Units / Rail |
| MC74HC132ADTR2G | TSSOP-14 (Pb-Free) | 2500 / Tape & Reel |
| NLV74HC132ADG* | SOIC-14 (Pb-Free) | 55 Units / Rail |
| NLV74HC132ADR2G* | SOIC-14 (Pb-Free) | 2500 / Tape & Reel |
| NLV74HC132ADTG* | TSSOP-14 (Pb-Free) | 96 Units / Rail |
| NLV74HC132ADTR2G* | TSSOP-14 (Pb-Free) | 2500 / Tape & Reel |
| NLV74HC132ANG* | PDIP-14 (Pb-Free) | 25 Units / Rail |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

MAXIMUM RATINGS

| Symbol | Parameter | | Value | Unit |
|-----------------------|--|--|---|------|
| V _{CC} | Positive DC Supply Voltage | | -0.5 to +7.0 | V |
| V _{IN} | Digital Input Voltage | | -0.5 to +7.0 | V |
| V _{OUT} | DC Output Voltage | Output in 3-State High or Low State | -0.5 to +7.0 $-0.5 \text{ to V}_{CC} +0.5$ | V |
| I _{IK} | Input Diode Current | | -20 | mA |
| I _{OK} | Output Diode Current | | ±20 | mA |
| l _{OUT} | DC Output Current, per Pin | | ±25 | mA |
| I _{CC} | DC Supply Current, V _{CC} and GND Pins | | ±75 | mA |
| I _{GND} | DC Ground Current per Ground Pin | | ±75 | mA |
| T _{STG} | Storage Temperature Range | | -65 to +150 | °C |
| TL | Lead Temperature, 1 mm from Case for 10 Seconds | | 260 | °C |
| TJ | Junction Temperature Under Bias | | + 150 | °C |
| θ_{JA} | Thermal Resistance | 14-PDIP 14-SOIC 14-TSSOP | 78 125 170 | °C/W |
| P _D | Power Dissipation in Still Air at 85°C | PDIP SOIC TSSOP | 750 500 450 | mW |
| MSL | Moisture Sensitivity | | Level 1 | |
| F _R | Flammability Rating Ox | kygen Index: 30% - 35% | UL 94 V0 @ 0.125 in | |
| V _{ESD} | | nan Body Model (Note 1) Machine Model (Note 2) d Device Model (Note 3) | > 2000 > 100 > 500 | V |
| I _{Latch-Up} | Latch-Up Performance Above V _{CC} and Below | w GND at 85°C (Note 4) | ±300 | mA |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Tested to EIA/JESD22-A114-A.

- 2. Tested to EIA/JESD22-A115-A.
- 3. Tested to JESD22-C101-A.
- 4. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|------------------------------------|--|------|----------------------|------|
| V _{CC} | DC Supply Voltage (Referenced to GND) | 2.0 | 6.0 | V |
| V _{IN} , V _{OUT} | DC Input Voltage, Output Voltage (Referenced to GND) | 0 | V _{CC} | V |
| T _A | Operating Temperature, All Package Types | - 55 | + 125 | °C |
| t _r , t _f | Input Rise and Fall Time (Figure 3) | - | No Limit (Note 5) | ns |

- 5. When V_{IN} ~ 0.5 V_{CC}, I_{CC} >> quiescent current.
 6. Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

| | V _{CC} Guaranteed Limit | | | | | | |
|--------------------------------|---|---|-------------------|--------------------|----------------------|----------------------|-------------|
| Symbol | Parameter | Test Conditions | ٧ | −55°C to 25°C | ≤ 85 °C | ≤125°C | Unit |
| V _{T+} max | Maximum Positive-Going Input Threshold Voltage (Figure 5) | $V_{OUT} = 0.1 \text{ V}$ $ I_{OUT} \le 20 \mu\text{A}$ | 2.0 4.5 6.0 | 1.5 3.15 4.2 | 1.5 3.15 4.2 | 1.5 3.15 4.2 | ٧ |
| V _{T+} min | Minimum Positive-Going Input Threshold Voltage (Figure 5) | $V_{OUT} = 0.1 \text{ V}$ $ I_{OUT} \le 20 \mu\text{A}$ | 2.0 4.5 6.0 | 1.0 2.3 3.0 | 0.95 2.25 2.95 | 0.95 2.25 2.95 | ٧ |
| V _T _max | Maximum Negative-Going Input Threshold Voltage (Figure 5) | $V_{OUT} = V_{CC} - 0.1 \text{ V}$ $ I_{OUT} \le 20 \mu\text{A}$ | 2.0 4.5 6.0 | 0.9 2.0 2.6 | 0.95 2.05 2.65 | 0.95 2.05 2.65 | ٧ |
| V _T _min | Minimum Negative-Going Input Threshold Voltage (Figure 5) | $V_{OUT} = V_{CC} - 0.1 \text{ V}$ $ I_{OUT} \le 20 \mu\text{A}$ | 2.0 4.5 6.0 | 0.3 0.9 1.2 | 0.3 0.9 1.2 | 0.3 0.9 1.2 | ٧ |
| V _H max (Note 7) | Maximum Hysteresis Voltage (Figure 5) | V_{OUT} = 0.1 V or V_{CC} – 0.1 V $ I_{OUT} \le 20 \mu A$ | 2.0 4.5 6.0 | 1.2 2.25 3.0 | 1.2 2.25 3.0 | 1.2 2.25 3.0 | > |
| V _H min (Note 7) | Minimum Hysteresis Voltage (Figure 5) | V_{OUT} = 0.1 V or V_{CC} – 0.1 V $ I_{OUT} \le 20 \mu A$ | 2.0 4.5 6.0 | 0.2 0.4 0.5 | 0.2 0.4 0.5 | 0.2 0.4 0.5 | > |
| V _{OH} | Minimum High-Level Output Voltage | $V_{IN} \leq V_{T}$ min or V_{T_+} max $ I_{OUT} \leq 20 \mu A$ | 2.0 4.5 6.0 | 1.9 4.4 5.9 | 1.9 4.4 5.9 | 1.9 4.4 5.9 | ٧ |
| | | $ \begin{array}{c c} V_{IN} \leq & -V_{T-} \text{min or } V_{T+} \text{max} \\ & I_{OUT} \leq 4.0 \text{ mA} \\ & I_{OUT} \leq 5.2 \text{ mA} \end{array} $ | 4.5 6.0 | 3.98 5.48 | 3.84 5.34 | 3.7 5.2 | |
| V _{OL} | Maximum Low-Level Output Voltage | $V_{IN} \ge V_{T+} max$ $ I_{OUT} \le 20 \mu A$ | 2.0 4.5 6.0 | 0.1 0.1 0.1 | 0.1 0.1 0.1 | 0.1 0.1 0.1 | V |
| | | $\label{eq:lout} \begin{array}{ l l } V_{IN} \geq V_{T_+} max & & I_{OUT} \leq 4.0 \ mA \\ & I_{OUT} \leq 5.2 \ mA \end{array}$ | 4.5 6.0 | 0.26 0.26 | 0.33 0.33 | 0.4 0.4 | |
| I _{IN} | Maximum Input Leakage Current | V _{IN} = V _{CC} or GND | 6.0 | ±0.1 | ±1.0 | ±1.0 | μΑ |
| I _{CC} | Maximum Quiescent Supply Current (per Package) | $V_{IN} = V_{CC}$ or GND $I_{OUT} = 0 \mu A$ | 6.0 | 1.0 | 10 | 40 | μΑ |

^{7.} $V_H min > (V_{T_+} min) - (V_{T_-} max); V_H max = (V_{T_+} max) + (V_{T_-} min).$

AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_{r} = t_{f} = 6.0 ns)

| | | V _{CC} | Guaranteed Limit | | | |
|--|---|-------------------|------------------|-----------------|-----------------|------|
| Symbol | Parameter | v | −55°C to 25°C | ≤ 85 °C | ≤125°C | Unit |
| t _{PLH} , t _{PHL} | Maximum Propagation Delay, Input A or B to Output Y (Figures 3 and 4) | 2.0 4.5 6.0 | 125 25 21 | 155 31 26 | 190 38 32 | ns |
| t _{TLH} , t _{THL} | Maximum Output Transition Time, Any Output (Figures 3 and 4) | 2.0 4.5 6.0 | 75 15 13 | 95 19 16 | 110 22 19 | ns |
| C _{in} | Maximum Input Capacitance | _ | 10 | 10 | 10 | pF |

| | | Typical @ 25°C, V _{CC} = 5.0 V | |
|----------|---|---|----|
| C_{PD} | Power Dissipation Capacitance (per Gate) (Note 8) | 24 | pF |

^{8.} Used to determine the no-load dynamic power consumption: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.

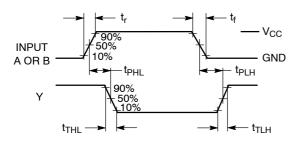
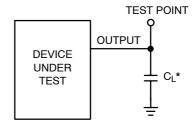


Figure 3. Switching Waveforms



*Includes all probe and jig capacitance

Figure 4. Test Circuit

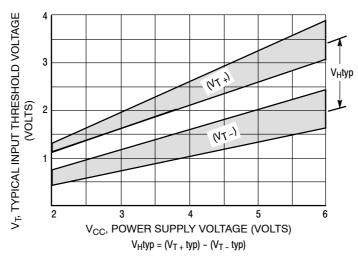


Figure 5. Typical Input Threshold, V_{T_+} , V_{T_-} Versus Power Supply Voltage

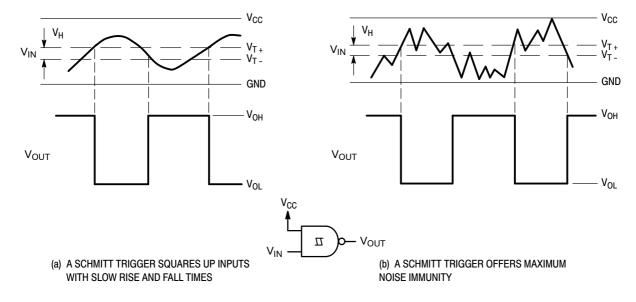
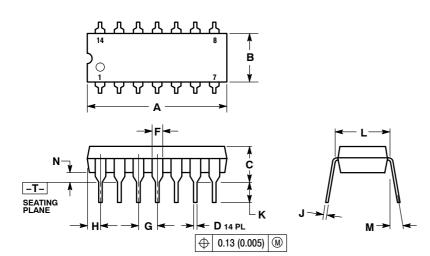


Figure 6. Typical Schmitt-Trigger Applications

PACKAGE DIMENSIONS

PDIP-14 **N SUFFIX** CASE 646-06 ISSUE P

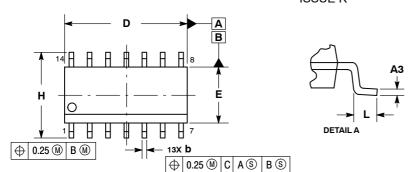


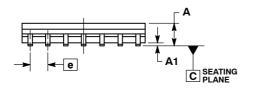
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

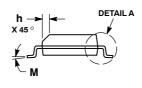
| | INCHES | | MILLIM | IETERS |
|-----|--------|-------|----------|--------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.715 | 0.770 | 18.16 | 19.56 |
| В | 0.240 | 0.260 | 6.10 | 6.60 |
| С | 0.145 | 0.185 | 3.69 | 4.69 |
| D | 0.015 | 0.021 | 0.38 | 0.53 |
| F | 0.040 | 0.070 | 1.02 | 1.78 |
| G | 0.100 | BSC | 2.54 BSC | |
| Н | 0.052 | 0.095 | 1.32 | 2.41 |
| J | 0.008 | 0.015 | 0.20 | 0.38 |
| K | 0.115 | 0.135 | 2.92 | 3.43 |
| L | 0.290 | 0.310 | 7.37 | 7.87 |
| М | | 10 ° | | 10 ° |
| N | 0.015 | 0.039 | 0.38 | 1.01 |

PACKAGE DIMENSIONS

SOIC-14 NB CASE 751A-03 ISSUE K







- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

 3. DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.

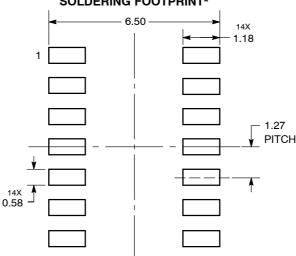
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.

 5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

 - SIDE.

| | MILLIMETERS | | INC | HES |
|-----|-------------|------|-------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 1.35 | 1.75 | 0.054 | 0.068 |
| A1 | 0.10 | 0.25 | 0.004 | 0.010 |
| А3 | 0.19 | 0.25 | 0.008 | 0.010 |
| b | 0.35 | 0.49 | 0.014 | 0.019 |
| D | 8.55 | 8.75 | 0.337 | 0.344 |
| Е | 3.80 | 4.00 | 0.150 | 0.157 |
| е | 1.27 | BSC | 0.050 | BSC |
| Н | 5.80 | 6.20 | 0.228 | 0.244 |
| h | 0.25 | 0.50 | 0.010 | 0.019 |
| L | 0.40 | 1.25 | 0.016 | 0.049 |
| М | 0 ° | 7° | 0 ° | 7° |

SOLDERING FOOTPRINT*

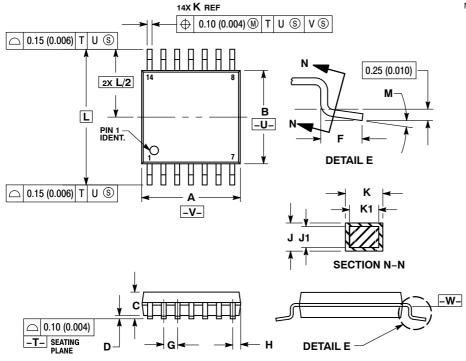


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-14 **DT SUFFIX** CASE 948G-01 ISSUE B



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER

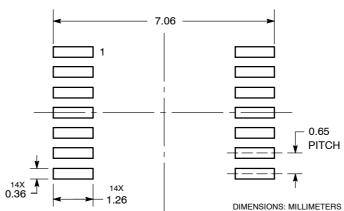
 - 1. DIMENSIONING AND TOLERANCING PER
 ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD
 FLASH, PROTRUSIONS OR GATE BURRS.
 MOLD FLASH OR GATE BURRS SHALL NOT
 EXCEED 0.15 (0.006) PER SIDE.
 - DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
 - INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL
 NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE
 DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08
 (0.003) TOTAL IN EXCESS OF THE K
 DIMENSION AT MAXIMUM MATERIAL
 CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY

 - REFERENCE ONLY.

 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| | MILLIN | IETERS | INC | HES | |
|-----|--------|--------|-----------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 4.90 | 5.10 | 0.193 | 0.200 | |
| В | 4.30 | 4.50 | 0.169 | 0.177 | |
| С | | 1.20 | | 0.047 | |
| D | 0.05 | 0.15 | 0.002 | 0.006 | |
| F | 0.50 | 0.75 | 0.020 | 0.030 | |
| G | 0.65 | BSC | 0.026 | BSC | |
| Н | 0.50 | 0.60 | 0.020 | 0.024 | |
| J | 0.09 | 0.20 | 0.004 | 0.008 | |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 | |
| Κ | 0.19 | 0.30 | 0.007 | 0.012 | |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 | |
| L | 6.40 | BSC | 0.252 BSC | | |
| М | 0 ° | 8 ° | 0 ° | 8 ° | |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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